

**CL04-15** Technical Specifications

## **FEATURES**

- High Overload Surge Capacity
- Durable Epoxy Resin Package



To order with quick disconnect terminals, use the **partnum-TERM** 

## **ABSOLUTE MAXIMUM RATINGS**

V <sub>RRM</sub>	Repeating Peak Reverse Voltage (kV):	15
$T_{JMAX}$	Max. junction temp.(°C):	130
T <sub>STG</sub>	Storage temp.(°C):	-40 to +13
Io	Avg. Forward Current (mA):	500
$I_{FSM}$	Forward Surge Current (A):	40

## **ELECTRICAL CHARACTERISTICS**

$I_{R1}$ Normal temp. Reverse Current ( $\mu A$ )			
@ $V_R = V_{RRM}$ , $T_{amb} = 25^{\circ}C$ :	5.0 ma		
$I_{R2}$ High temp. Reverse Current ( $\mu$ A)			
@ $V_R = V_{RRM}, T_{amb} = 100^{\circ}C$ :	50 max		
V <sub>F</sub> Forward Voltage Drop (V)			
@ I <sub>F</sub> =500mA:	13.0		
Reverse Breakdown Voltage (kV)			
@ I <sub>R</sub> =100µA:	≥15		
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## **TEST CONDITIONS**

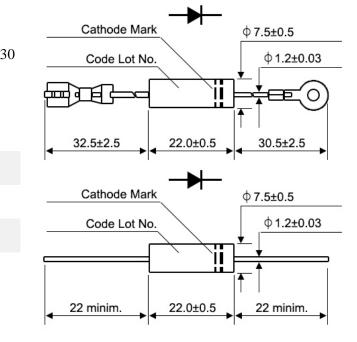
High temp. Reverse Voltage @ 1000 hrs.:

High temp. storage @ 1000 Hrs.: Soldering Resistance Heat Test:

High pressure smoke test @ 10 hrs.: Insulation Resistance Test (1000M $\Omega$ ): Insulation Strength Test @ 10KV: Lead bend test: Lead pull test:

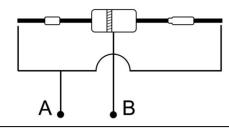
Insulation resistance test condition: Measure between A and B by using a DC 500V Insulation resistance tester

Insulation strength test condition: Apply half sine wave voltage with 10kV wave height between A and B in insulation liquid



 $V_{RM}=V_{RRM}$ , f=50Hz,  $T_{AMB}=100^{\circ}$ C Half sine voltage with f=50Hz applied,  $T_{AMB}=100^{\circ}$ C  $T_{AMB}=130\pm2^{\circ}$ C Solder trough temp.: 350±10°C, Dip Time: 3.5s ± 0.5s 120°C, 2 x 10<sup>5</sup>pa Between the center of the body and terminal (*See Fig. 1*) 1 min. between center of the body and terminal. (*Fig.1*) Force 10 N to the lead, bent it to pos. and neg. 90°

Force 70 N of axial to the lead for 1 min.



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